

Title (en)

TAPE APPLICATION METHOD AND TAPE APPLICATION DEVICE

Title (de)

BANDAUFBRINGVERFAHREN UND BANDAUFBRINGVORRICHTUNG

Title (fr)

PROCÉDÉ ET DISPOSITIF D'APPLICATION DE BANDES

Publication

**EP 2144833 B1 20101027 (DE)**

Application

**EP 08716307 A 20080306**

Priority

- EP 2008001792 W 20080306
- DE 202007003696 U 20070311

Abstract (en)

[origin: US2009320997A1] A method and device (1) are provided for applying laminated tapes (2, 3) with an adhesive tape (2) and a cover tape (3) on a surface (4). The tape application device (1) includes a frame (5), a tape winder (8) for the laminated tape (2, 3), a tape winder (9) for the pulled-off cover tape (3), a tape guide (14) and a pressure-exerting device (18) for pressing the adhesive tape (2) onto a surface (4). During application, the cover tape (3) is at some parts detached and guided away from the adhesive tape (2), wherein the adhesive tape (2) can be severed at the detachment point and can be pressed onto the surface (4) with two closely adjacent pressing elements (19, 20).

IPC 8 full level

**B65H 19/10** (2006.01)

CPC (source: EP US)

**B65H 19/102** (2013.01 - EP US); **B65H 2301/46064** (2013.01 - EP US); **Y10S 156/919** (2013.01 - EP US); **Y10S 156/931** (2013.01 - EP US); **Y10S 156/935** (2013.01 - EP US); **Y10T 156/1028** (2015.01 - EP US); **Y10T 156/1062** (2015.01 - EP US); **Y10T 156/1075** (2015.01 - EP US); **Y10T 156/1077** (2015.01 - EP US); **Y10T 156/1085** (2015.01 - EP US); **Y10T 156/1174** (2015.01 - EP US); **Y10T 156/1348** (2015.01 - EP US); **Y10T 156/1795** (2015.01 - EP US); **Y10T 156/195** (2015.01 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

DOCDB simple family (publication)

**US 2009320997 A1 20091231**; **US 8057627 B2 20111115**; AT E486034 T1 20101115; DE 202007003696 U1 20080717; DE 502008001662 D1 20101209; EP 2144833 A1 20100120; EP 2144833 B1 20101027; WO 2008116548 A1 20081002

DOCDB simple family (application)

**US 44475608 A 20080306**; AT 08716307 T 20080306; DE 202007003696 U 20070311; DE 502008001662 T 20080306; EP 08716307 A 20080306; EP 2008001792 W 20080306